L	Hits	Search Text	DB	Time stamp
Number				
1	2528010		USPAT;	2004/06/09
		circuit) dice	US-PGPUB;	04:43
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	1843861	sheet (silicone with rubber) silicone	USPAT;	2004/06/09
			US-PGPUB;	04:43
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
3	351061		USPAT;	2004/06/09
		radition slug plate dissipate dissipation	US-PGPUB;	04:44
		dissipated)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	1948566	resin polyamide polyimide	USPAT;	2004/06/09
			US-PGPUB;	04:44
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	
5	190	, <u>-</u>	USPAT;	2004/06/09
		adj circuit) dice) same (sheet (silicone	US-PGPUB;	04:46
		with rubber) silicone) same (heat with	EPO; JPO;	
		(plate sink radiate radiating radition	DERWENT;	
		slug plate dissipate dissipation	IBM_TDB	
		dissipated)) same (resin polyamide		
_	05.5	polyimide) same "5"		1
6	856		USPAT;	2004/06/09
		adj circuit) dice) same (sheet (silicone	US-PGPUB;	04:47
		with rubber) silicone) same (heat with	EPO; JPO;	
		(plate sink radiate radiating radition	DERWENT;	1
		slug plate dissipate dissipation	IBM_TDB	
	1	dissipated)) same (resin polyamide		
7	1 222	polyimide)		
7	339	, ,	USPAT;	2004/06/09
	1	adj circuit) dice) same (sheet (silicone	US-PGPUB;	04:48
		with rubber) silicone) same (heat with	EPO; JPO;	
	1	(plate sink radiate radiating radition	DERWENT;	
		slug plate dissipate dissipation	IBM_TDB	
		dissipated)) same (resin polyamide		
	1	polyimide)) and solder		<u></u>

L Number	Hits	Search Text	DB	Time stamp
1	2528010	die chip semiconductor ic (integrated adj circuit) dice	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/09 04:43
2	1843861	sheet (silicone with rubber) silicone	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/09 04:48
3	351061	heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/09 04:44
4	1948566	resin polyamide polyimide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/09 04:44
5	190	(die chip semiconductor ic (integrated adj circuit) dice) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide) same "5"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:46
7	339		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:48
6	856	(die chip semiconductor ic (integrated adj circuit) dice) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:48
8	223	(((die chip semiconductor ic (integrated adj circuit) dice) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide)) and solder) and ((silicone with rubber) silicone rubber)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:48

L	Hits	Search Text	DB	Time stamp
Number				_
1	247243	polyamide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/09 10:19
2	223	<pre>(((die chip semiconductor ic (integrated adj circuit) dice) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide)) and solder) and ((silicone with rubber) silicone rubber)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 10:20
3	257783	polyamide amd ((((die chip semiconductor ic (integrated adj circuit) dice) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide)) and solder) and ((silicone with rubber) silicone rubber))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 10:20
	. 44	polyamide and ((((die chip semiconductor ic (integrated adj circuit) dice) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide)) and solder) and ((silicone with rubber) silicone rubber))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 10:20